

## Electronic Patent Application Fee Transmittal

Application Number:	10717122			
Filing Date:	19-Nov-2003			
Title of Invention:	Dielectric barrier layer for a copper metallization layer having a varying silicon concentration along its thickness			
First Named Inventor/Applicant Name:	Larry Zhao			
Filer:	J. Mike Amerson/Mary Paul			
Attorney Docket Number:	2000.106900			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1020</b>